



TAOGLAS®



Datasheet

SMD Mount Receptacle

Part No:
RECE.20369.001E.01

Description:

SMD W.FL Compatible Receptacle

Compatible with I-PEX MHFIII, Hirose W.FL, Hirose W.FL2

Features:

Mating Height: 1.6mm Max

5000pcs per reel

Dimensions: 2 x 2 x 0.85 mm

Diameter: 1.4mm

RoHS & Reach Compliant

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Changelog

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1. Introduction



Part of the Taoglas SMD Mount Receptacle the RECE.20369.001E.01 is a 3-pad type wire-to-board SMD Receptacle solution that is ultra-small, lightweight and low profile (1.6mm MAX.) with an operational frequency range of DC to 6 GHz. Taoglas the RECE.20369.001E.01 is gold plated to have superior performance and allow easy mounting of the male RF connector.

Packaged on tape and reel, this receptacle is designed to be placed with automatic “pick and place” equipment for ease of installation.

The RECE.20369.001E.01 acts as a 50 Ohm transmission line to connect the micro-miniature RF connector to the printed circuit board. It is fully compatible with I-PEX MHFIII, Hirose W.FL and all other available W.FL compatible connectors .

Applicable Technologies:

The RECE.20369.001E.01 receptacles are commonly integrated into GSM module, GPS module, Wireless LAN modules.

For further information, please contact your regional Taoglas customer support team.

2. Specifications

Electrical	
Operation Frequency	DC to 6 GHz
VSWR	1.3 Max at DC~3 GHz
	1.4 Max at 3~6 GHz
Nominal Impedance	50 Ohm
Rated Voltage	60V AC
Rated Current	1A Max.
Contact Resistance	Subject mated contacts assembled in housing to 20mV Max. open circuit at 10mA Max
Withstand Voltage	AC 200V/minute
Insulation Resistance	Impressed voltage 100V DC for 1min Initial : 500MΩ Min. Final : 100MΩ Min.
Dielectric Withstanding Voltage	200V AC for 1 minute
Current leakage	0.5mA Max
Temperature	-40 to +90°C

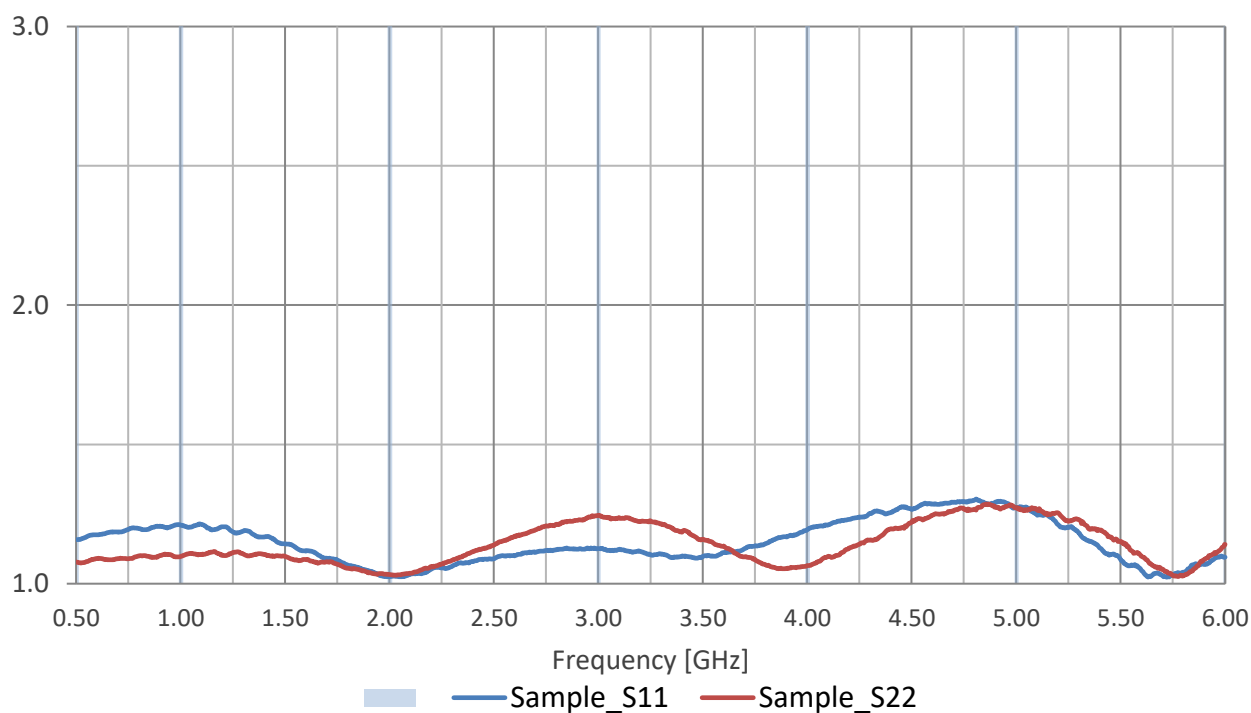
Material	
Outer Contact	Copper Alloy (Au plating)
Centre Contact	Copper Alloy (Au plating)
Insulator	LCP UL94-V0

Environmental	
Durability per EIA-364-09C (2-3 cycles per min @ 30 cycles)	
Vibration	10Hz -> 100Hz -> 10Hz for 20 mins.
Peak value of acceleration	1.5mm or 59m/s ² (6G)
Direction	3 axis 5 Cycles
Mechanical Shock	
Accelerate Velocity	735m/s ² (75G)
Waveform	Half-sine shock plus.
Duration	11m sec.
Direct Current	1mA
Direction	In ±X, ±Y and ±Z axes.
Cycle	3 cycles for each direction, totally 18 cycles

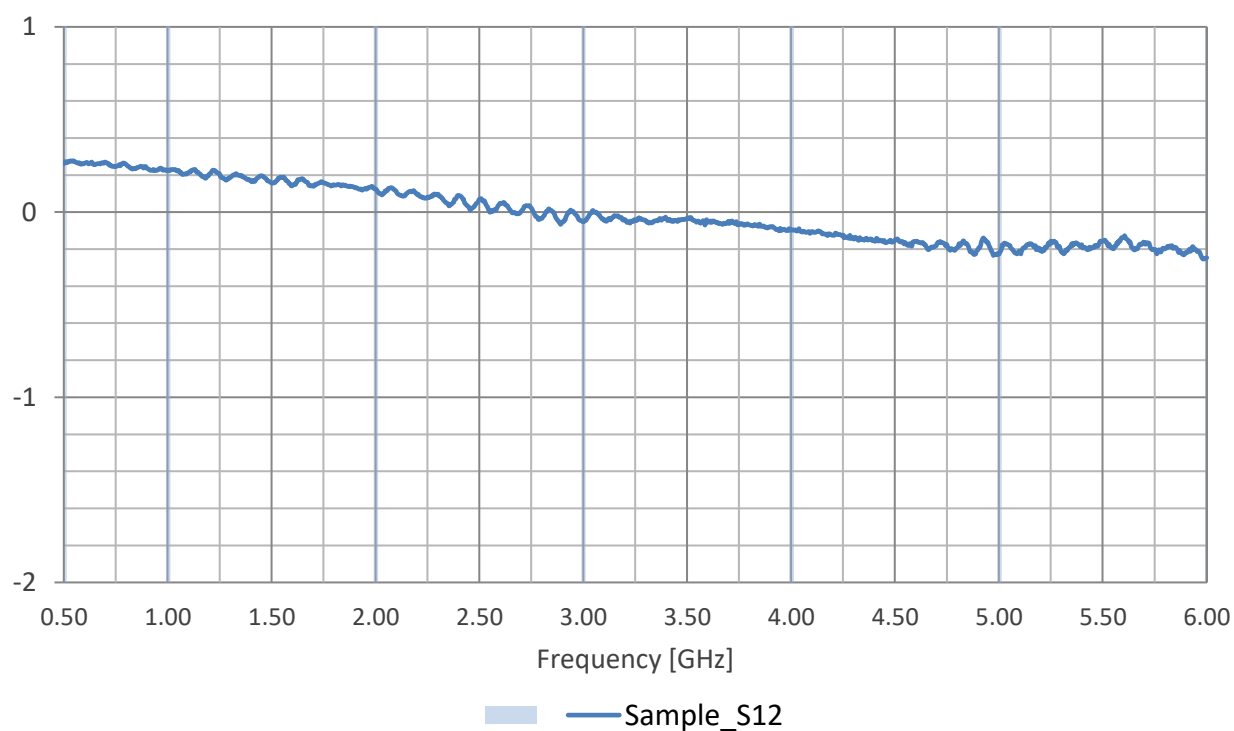
Thermal Shock (40°C for 30mins to 5~35°C for 5 minutes to 90°C for 30mins to 5~35°C for 5 minutes)	
Transition Time	5 minutes
Cycles	5
Humidity	90~95% RH
Temperature	40+/- 2°C
Duration	96 hours
Salt Water Spray	
Temperature	35+/- 2°C
Salt Water Density	5+/-1% (by weight)
Duration	48 Hours
High temperature life	90+/- 2°C for 96 hours
Cold temperature life	-40+/- 2°C for 96 hours
H2S gas	
Temperature	40+/-2°C
Relative Humidity	80 +/-5% RH
Gas H2S	3+/-1 ppm
Duration	96 Hours
Moisture Sensitivity Level	3

3. Connector Data

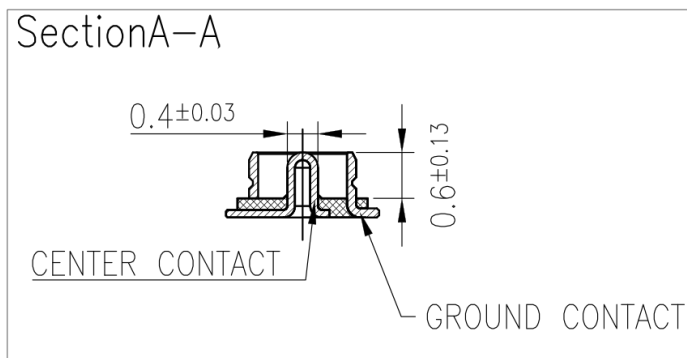
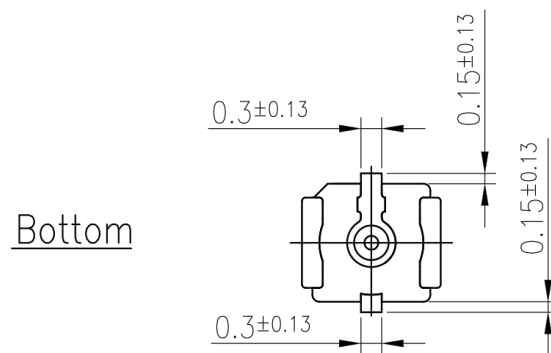
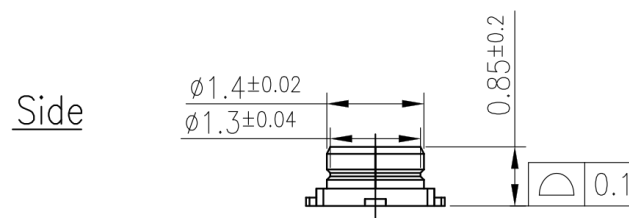
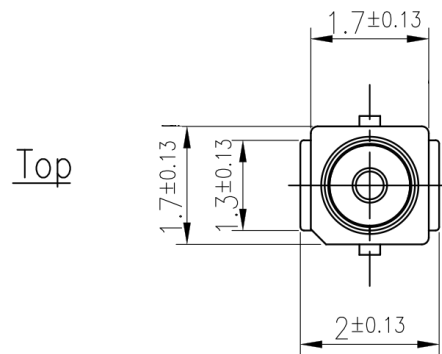
3.1 VSWR



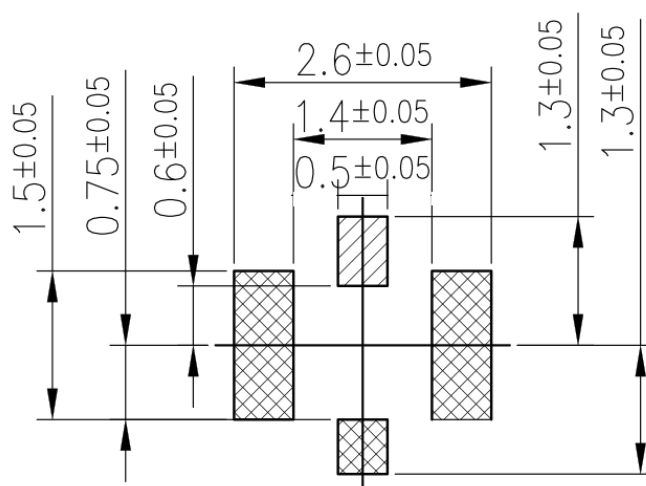
3.2 Insertion Loss



4. Mechanical Drawing (Units: mm)



5. Footprint

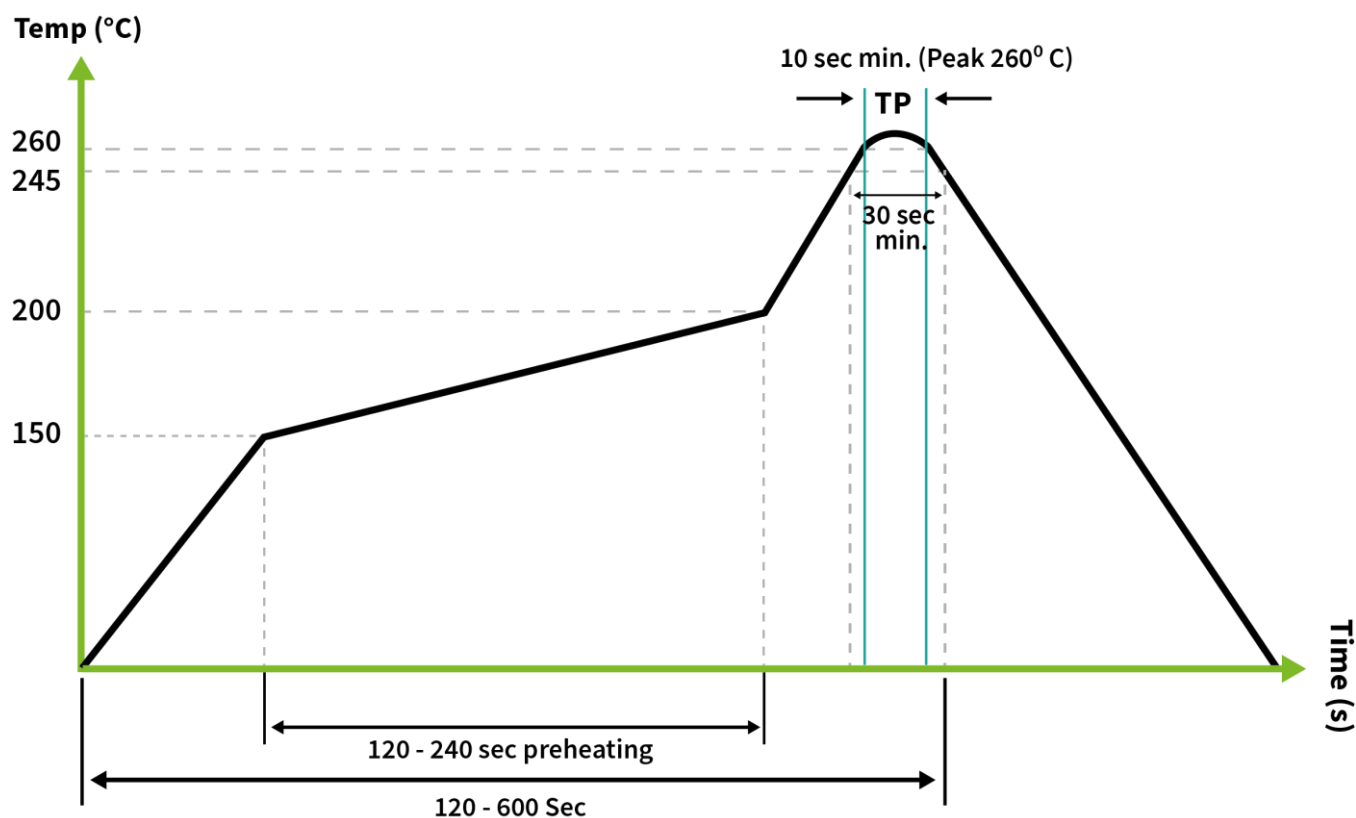


Notes:

- 1. CENTER CONTACT 
- 2. GROUND CONTACT 

6. Solder Reflow

The RECE.20369.001E.01 can be assembled by following the recommended soldering temperatures are as follows:



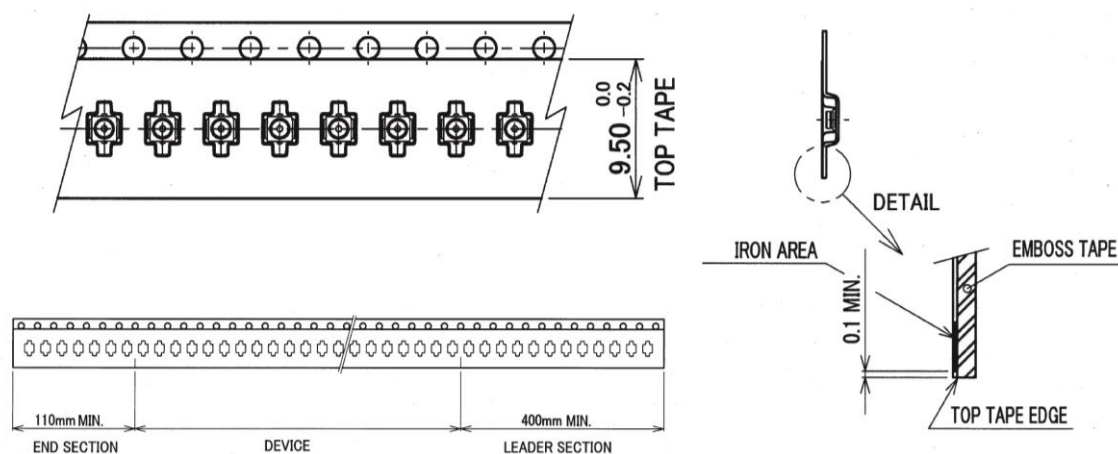
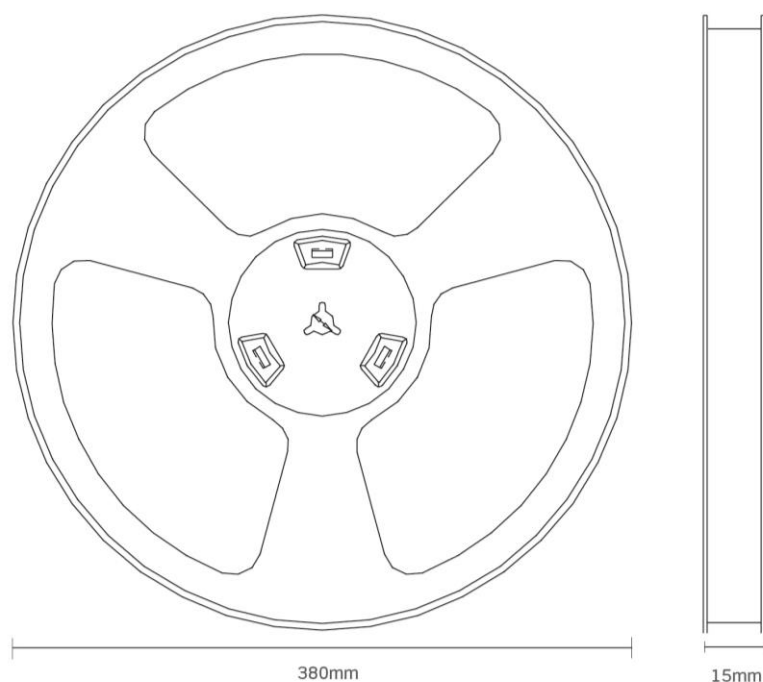
*Temperatures listed within a tolerance of $\pm 10^\circ \text{C}$

Smaller components are typically mounted on the first pass, however, we do advise mounting the RECE.20369.001E.01 when placing larger components on the board during subsequent reflows.

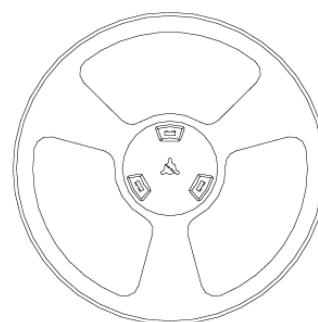
Note: Soldering flux classified ROL0 under IPC J-STD-004 is recommended.

7. Packaging

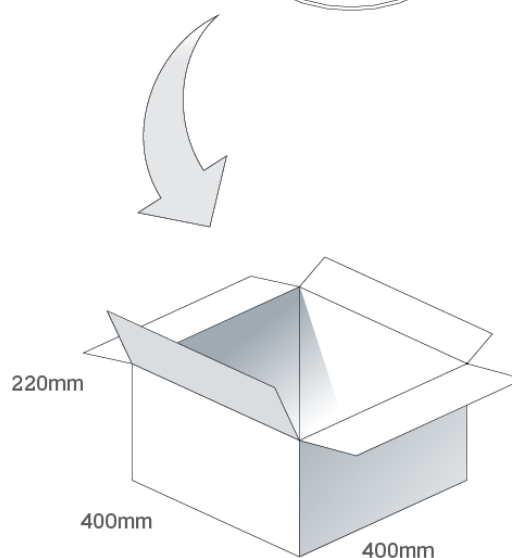
5000 pcs RECE.20369.001E.01 reel
 Dimensions - 380*380*15mm
 Weight -262g



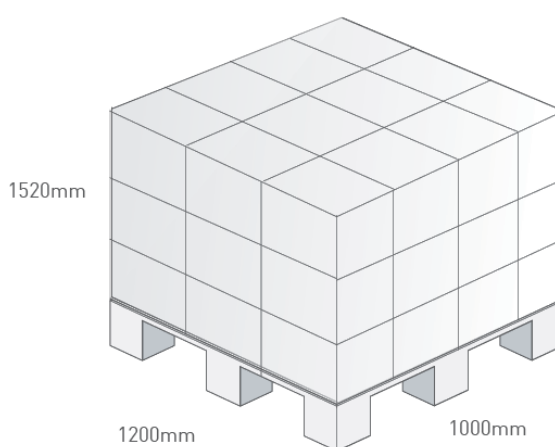
5000 pcs RECE.20369.001E.01 reel
Dimensions - 380*380*15mm
Weight - 262g



8 reels, 40000 pcs in one carton
Carton Dimensions - 400*400*220mm
Weight - 3.5Kg



Pallet Dimensions 1200*1000*1520mm
36 Cartons per Pallet
12 Cartons per layer
3 Layers



Changelog for the datasheet

SPE-16-8-033 - RECE.20369.001E.01

Revision: F (Current Version)

Date:	2023-09-07
Changes:	Updated Solder Reflow Information
Changes Made by:	Cesar Sousa

Previous Revisions

Revision: E

Date:	2023-03-03
Changes:	Updated description
Changes Made by:	Cesar Sousa

Revision: D

Date:	2022-01-27
Changes:	Updated Solder Reflow Diagram & Adding MSL.
Changes Made by:	Gary West

Revision: C

Date:	2021-07-15
Changes:	Updated Solder Reflow Diagram & Adding MSL.
Changes Made by:	Gary West

Revision: B

Date:	2021-02-03
Changes:	Following EC-20-8-036
Changes Made by:	Jack Conroy

Revision: A (Original First Release)

Date: 2016-04-21

Notes:

Author: Jack Conroy



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